



Welcome to [E-XFL.COM](#)

Understanding **Embedded - FPGAs (Field Programmable Gate Array)**

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details

Product Status	Obsolete
Number of LABs/CLBs	185000
Number of Logic Elements/Cells	490000
Total RAM Bits	46080000
Number of I/O	696
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-FBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxma5k3f40c2ln

Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 2 of 2)

Symbol	Description	Minimum	Maximum	Unit
V_{CCD_FPLL}	PLL digital power supply	-0.5	1.8	V
V_{CCA_FPLL}	PLL analog power supply	-0.5	3.4	V
V_I	DC input voltage	-0.5	3.8	V
T_J	Operating junction temperature	-55	125	°C
T_{STG}	Storage temperature (No bias)	-65	150	°C
I_{OUT}	DC output current per pin	-25	40	mA

Table 4 lists the absolute conditions for the transceiver power supply for Stratix V GX, GS, and GT devices.

Table 4. Transceiver Power Supply Absolute Conditions for Stratix V GX, GS, and GT Devices

Symbol	Description	Devices	Minimum	Maximum	Unit
V_{CCA_GXBL}	Transceiver channel PLL power supply (left side)	GX, GS, GT	-0.5	3.75	V
V_{CCA_GXBR}	Transceiver channel PLL power supply (right side)	GX, GS	-0.5	3.75	V
V_{CCA_GTBR}	Transceiver channel PLL power supply (right side)	GT	-0.5	3.75	V
V_{CCHIP_L}	Transceiver hard IP power supply (left side)	GX, GS, GT	-0.5	1.35	V
V_{CCHIP_R}	Transceiver hard IP power supply (right side)	GX, GS, GT	-0.5	1.35	V
V_{CCHSSI_L}	Transceiver PCS power supply (left side)	GX, GS, GT	-0.5	1.35	V
V_{CCHSSI_R}	Transceiver PCS power supply (right side)	GX, GS, GT	-0.5	1.35	V
V_{CCR_GXBL}	Receiver analog power supply (left side)	GX, GS, GT	-0.5	1.35	V
V_{CCR_GXBR}	Receiver analog power supply (right side)	GX, GS, GT	-0.5	1.35	V
V_{CCR_GTBR}	Receiver analog power supply for GT channels (right side)	GT	-0.5	1.35	V
V_{CCT_GXBL}	Transmitter analog power supply (left side)	GX, GS, GT	-0.5	1.35	V
V_{CCT_GXBR}	Transmitter analog power supply (right side)	GX, GS, GT	-0.5	1.35	V
V_{CCT_GTBR}	Transmitter analog power supply for GT channels (right side)	GT	-0.5	1.35	V
V_{CCL_GTBR}	Transmitter clock network power supply (right side)	GT	-0.5	1.35	V
V_{CCH_GXBL}	Transmitter output buffer power supply (left side)	GX, GS, GT	-0.5	1.8	V
V_{CCH_GXBR}	Transmitter output buffer power supply (right side)	GX, GS, GT	-0.5	1.8	V

Maximum Allowed Overshoot and Undershoot Voltage

During transitions, input signals may overshoot to the voltage shown in Table 5 and undershoot to -2.0 V for input currents less than 100 mA and periods shorter than 20 ns.

Recommended Operating Conditions

This section lists the functional operating limits for the AC and DC parameters for Stratix V devices. Table 6 lists the steady-state voltage and current values expected from Stratix V devices. Power supply ramps must all be strictly monotonic, without plateaus.

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 1 of 2)

Symbol	Description	Condition	Min ⁽⁴⁾	Typ	Max ⁽⁴⁾	Unit
V_{CC}	Core voltage and periphery circuitry power supply (C1, C2, I2, and I3YY speed grades)	—	0.87	0.9	0.93	V
	Core voltage and periphery circuitry power supply (C2L, C3, C4, I2L, I3, I3L, and I4 speed grades) ⁽³⁾	—	0.82	0.85	0.88	V
V_{CCPT}	Power supply for programmable power technology	—	1.45	1.50	1.55	V
V_{CC_AUX}	Auxiliary supply for the programmable power technology	—	2.375	2.5	2.625	V
V_{CCPD} ⁽¹⁾	I/O pre-driver (3.0 V) power supply	—	2.85	3.0	3.15	V
	I/O pre-driver (2.5 V) power supply	—	2.375	2.5	2.625	V
V_{CCIO}	I/O buffers (3.0 V) power supply	—	2.85	3.0	3.15	V
	I/O buffers (2.5 V) power supply	—	2.375	2.5	2.625	V
	I/O buffers (1.8 V) power supply	—	1.71	1.8	1.89	V
	I/O buffers (1.5 V) power supply	—	1.425	1.5	1.575	V
	I/O buffers (1.35 V) power supply	—	1.283	1.35	1.45	V
	I/O buffers (1.25 V) power supply	—	1.19	1.25	1.31	V
	I/O buffers (1.2 V) power supply	—	1.14	1.2	1.26	V
	Configuration pins (3.0 V) power supply	—	2.85	3.0	3.15	V
V_{CCPGM}	Configuration pins (2.5 V) power supply	—	2.375	2.5	2.625	V
	Configuration pins (1.8 V) power supply	—	1.71	1.8	1.89	V
V_{CCA_FPLL}	PLL analog voltage regulator power supply	—	2.375	2.5	2.625	V
V_{CCD_FPLL}	PLL digital voltage regulator power supply	—	1.45	1.5	1.55	V
V_{CCBAT} ⁽²⁾	Battery back-up power supply (For design security volatile key register)	—	1.2	—	3.0	V
V_I	DC input voltage	—	-0.5	—	3.6	V
V_0	Output voltage	—	0	—	V_{CCIO}	V
T_J	Operating junction temperature	Commercial	0	—	85	°C
		Industrial	-40	—	100	°C

Table 18. Single-Ended SSTL, HSTL, and HSUL I/O Reference Voltage Specifications for Stratix V Devices

I/O Standard	V _{CCIO} (V)			V _{REF} (V)			V _{TT} (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}	V _{REF} – 0.04	V _{REF}	V _{REF} + 0.04
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	V _{REF} – 0.04	V _{REF}	V _{REF} + 0.04
SSTL-15 Class I, II	1.425	1.5	1.575	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}
SSTL-135 Class I, II	1.283	1.35	1.418	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}
SSTL-125 Class I, II	1.19	1.25	1.26	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}
SSTL-12 Class I, II	1.14	1.20	1.26	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	—	V _{CCIO} /2	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	—	V _{CCIO} /2	—
HSTL-12 Class I, II	1.14	1.2	1.26	0.47 * V _{CCIO}	0.5 * V _{CCIO}	0.53 * V _{CCIO}	—	V _{CCIO} /2	—
HSUL-12	1.14	1.2	1.3	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}	—	—	—

Table 19. Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Stratix V Devices (Part 1 of 2)

I/O Standard	V _{IL(DC)} (V)		V _{IH(DC)} (V)		V _{IL(AC)} (V)	V _{IH(AC)} (V)	V _{OL} (V)	V _{OH} (V)	I _{ol} (mA)	I _{oh} (mA)
	Min	Max	Min	Max						
SSTL-2 Class I	-0.3	V _{REF} – 0.15	V _{REF} + 0.15	V _{CCIO} + 0.3	V _{REF} – 0.31	V _{REF} + 0.31	V _{TT} – 0.608	V _{TT} + 0.608	8.1	-8.1
SSTL-2 Class II	-0.3	V _{REF} – 0.15	V _{REF} + 0.15	V _{CCIO} + 0.3	V _{REF} – 0.31	V _{REF} + 0.31	V _{TT} – 0.81	V _{TT} + 0.81	16.2	-16.2
SSTL-18 Class I	-0.3	V _{REF} – 0.125	V _{REF} + 0.125	V _{CCIO} + 0.3	V _{REF} – 0.25	V _{REF} + 0.25	V _{TT} – 0.603	V _{TT} + 0.603	6.7	-6.7
SSTL-18 Class II	-0.3	V _{REF} – 0.125	V _{REF} + 0.125	V _{CCIO} + 0.3	V _{REF} – 0.25	V _{REF} + 0.25	0.28	V _{CCIO} – 0.28	13.4	-13.4
SSTL-15 Class I	—	V _{REF} – 0.1	V _{REF} + 0.1	—	V _{REF} – 0.175	V _{REF} + 0.175	0.2 * V _{CCIO}	0.8 * V _{CCIO}	8	-8
SSTL-15 Class II	—	V _{REF} – 0.1	V _{REF} + 0.1	—	V _{REF} – 0.175	V _{REF} + 0.175	0.2 * V _{CCIO}	0.8 * V _{CCIO}	16	-16
SSTL-135 Class I, II	—	V _{REF} – 0.09	V _{REF} + 0.09	—	V _{REF} – 0.16	V _{REF} + 0.16	0.2 * V _{CCIO}	0.8 * V _{CCIO}	—	—
SSTL-125 Class I, II	—	V _{REF} – 0.85	V _{REF} + 0.85	—	V _{REF} – 0.15	V _{REF} + 0.15	0.2 * V _{CCIO}	0.8 * V _{CCIO}	—	—
SSTL-12 Class I, II	—	V _{REF} – 0.1	V _{REF} + 0.1	—	V _{REF} – 0.15	V _{REF} + 0.15	0.2 * V _{CCIO}	0.8 * V _{CCIO}	—	—

Table 19. Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Stratix V Devices (Part 2 of 2)

I/O Standard	V _{IL(DC)} (V)		V _{IH(DC)} (V)		V _{IL(AC)} (V)	V _{IH(AC)} (V)	V _{OL} (V)	V _{OH} (V)	I _{ol} (mA)	I _{oh} (mA)
	Min	Max	Min	Max	Max	Min	Max	Min		
HSTL-18 Class I	—	V _{REF} – 0.1	V _{REF} + 0.1	—	V _{REF} – 0.2	V _{REF} + 0.2	0.4	V _{CCIO} – 0.4	8	-8
HSTL-18 Class II	—	V _{REF} – 0.1	V _{REF} + 0.1	—	V _{REF} – 0.2	V _{REF} + 0.2	0.4	V _{CCIO} – 0.4	16	-16
HSTL-15 Class I	—	V _{REF} – 0.1	V _{REF} + 0.1	—	V _{REF} – 0.2	V _{REF} + 0.2	0.4	V _{CCIO} – 0.4	8	-8
HSTL-15 Class II	—	V _{REF} – 0.1	V _{REF} + 0.1	—	V _{REF} – 0.2	V _{REF} + 0.2	0.4	V _{CCIO} – 0.4	16	-16
HSTL-12 Class I	-0.15	V _{REF} – 0.08	V _{REF} + 0.08	V _{CCIO} + 0.15	V _{REF} – 0.15	V _{REF} + 0.15	0.25*	V _{CCIO}	8	-8
HSTL-12 Class II	-0.15	V _{REF} – 0.08	V _{REF} + 0.08	V _{CCIO} + 0.15	V _{REF} – 0.15	V _{REF} + 0.15	0.25*	V _{CCIO}	16	-16
HSUL-12	—	V _{REF} – 0.13	V _{REF} + 0.13	—	V _{REF} – 0.22	V _{REF} + 0.22	0.1*	V _{CCIO}	0.9*	—

Table 20. Differential SSTL I/O Standards for Stratix V Devices

I/O Standard	V _{CCIO} (V)			V _{SWING(DC)} (V)		V _{X(AC)} (V)			V _{SWING(AC)} (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.3	V _{CCIO} + 0.6	V _{CCIO} /2 – 0.2	—	V _{CCIO} /2 + 0.2	0.62	V _{CCIO} + 0.6
SSTL-18 Class I, II	1.71	1.8	1.89	0.25	V _{CCIO} + 0.6	V _{CCIO} /2 – 0.175	—	V _{CCIO} /2 + 0.175	0.5	V _{CCIO} + 0.6
SSTL-15 Class I, II	1.425	1.5	1.575	0.2	(¹)	V _{CCIO} /2 – 0.15	—	V _{CCIO} /2 + 0.15	0.35	—
SSTL-135 Class I, II	1.283	1.35	1.45	0.2	(¹)	V _{CCIO} /2 – 0.15	V _{CCIO} /2	V _{CCIO} /2 + 0.15	2(V _{IH(AC)} – V _{REF})	2(V _{IL(AC)} – V _{REF})
SSTL-125 Class I, II	1.19	1.25	1.31	0.18	(¹)	V _{CCIO} /2 – 0.15	V _{CCIO} /2	V _{CCIO} /2 + 0.15	2(V _{IH(AC)} – V _{REF})	—
SSTL-12 Class I, II	1.14	1.2	1.26	0.18	—	V _{REF} – 0.15	V _{CCIO} /2	V _{REF} + 0.15	-0.30	0.30

Note to Table 20:

- (1) The maximum value for V_{SWING(DC)} is not defined. However, each single-ended signal needs to be within the respective single-ended limits (V_{IH(DC)} and V_{IL(DC)}).

Table 21. Differential HSTL and HSUL I/O Standards for Stratix V Devices (Part 1 of 2)

I/O Standard	V _{CCIO} (V)			V _{DIF(DC)} (V)		V _{X(AC)} (V)			V _{CM(DC)} (V)			V _{DIF(AC)} (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Typ	Max	Min	Max
HSTL-18 Class I, II	1.71	1.8	1.89	0.2	—	0.78	—	1.12	0.78	—	1.12	0.4	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.2	—	0.68	—	0.9	0.68	—	0.9	0.4	—

-  You typically use the interactive Excel-based Early Power Estimator before designing the FPGA to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.
-  For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

Table 23. Transceiver Specifications for Stratix V GX and GS Devices ⁽¹⁾ (Part 2 of 7)

Symbol/ Description	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Spread-spectrum downspread	PCIe	—	0 to -0.5	—	—	0 to -0.5	—	—	0 to -0.5	—	%
On-chip termination resistors ⁽²⁾	—	—	100	—	—	100	—	—	100	—	Ω
Absolute V _{MAX} ⁽⁵⁾	Dedicated reference clock pin	—	—	1.6	—	—	1.6	—	—	1.6	V
	RX reference clock pin	—	—	1.2	—	—	1.2	—	—	1.2	
Absolute V _{MIN}	—	-0.4	—	—	-0.4	—	—	-0.4	—	—	V
Peak-to-peak differential input voltage	—	200	—	1600	200	—	1600	200	—	1600	mV
V _{ICM} (AC coupled) ⁽³⁾	Dedicated reference clock pin	1050/1000/900/850 ⁽²⁾			1050/1000/900/850 ⁽²⁾			1050/1000/900/850 ⁽²⁾			mV
	RX reference clock pin	1.0/0.9/0.85 ⁽⁴⁾			1.0/0.9/0.85 ⁽⁴⁾			1.0/0.9/0.85 ⁽⁴⁾			V
V _{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250	—	550	250	—	550	250	—	550	mV
Transmitter REFCLK Phase Noise (622 MHz) ⁽²⁰⁾	100 Hz	—	—	-70	—	—	-70	—	—	-70	dBc/Hz
	1 kHz	—	—	-90	—	—	-90	—	—	-90	dBc/Hz
	10 kHz	—	—	-100	—	—	-100	—	—	-100	dBc/Hz
	100 kHz	—	—	-110	—	—	-110	—	—	-110	dBc/Hz
	≥1 MHz	—	—	-120	—	—	-120	—	—	-120	dBc/Hz
Transmitter REFCLK Phase Jitter (100 MHz) ⁽¹⁷⁾	10 kHz to 1.5 MHz (PCIe)	—	—	3	—	—	3	—	—	3	ps (rms)
R _{REF} ⁽¹⁹⁾	—	—	1800 ±1%	—	—	1800 ±1%	—	—	180 0 ±1%	—	Ω
Transceiver Clocks											
fixedclk clock frequency	PCIe Receiver Detect	—	100 or 125	—	—	100 or 125	—	—	100 or 125	—	MHz

Table 24 shows the maximum transmitter data rate for the clock network.

Table 24. Clock Network Maximum Data Rate Transmitter Specifications ⁽¹⁾

Clock Network	ATX PLL			CMU PLL ⁽²⁾			fPLL		
	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span
x1 ⁽³⁾	14.1	—	6	12.5	—	6	3.125	—	3
x6 ⁽³⁾	—	14.1	6	—	12.5	6	—	3.125	6
x6 PLL Feedback ⁽⁴⁾	—	14.1	Side-wide	—	12.5	Side-wide	—	—	—
xN (PCIe)	—	8.0	8	—	5.0	8	—	—	—
xN (Native PHY IP)	8.0	8.0	Up to 13 channels above and below PLL	7.99	7.99	Up to 13 channels above and below PLL	3.125	3.125	Up to 13 channels above and below PLL
	—	8.01 to 9.8304	Up to 7 channels above and below PLL						

Notes to Table 24:

- (1) Valid data rates below the maximum specified in this table depend on the reference clock frequency and the PLL counter settings. Check the MegaWizard message during the PHY IP instantiation.
- (2) ATX PLL is recommended at 8 Gbps and above data rates for improved jitter performance.
- (3) Channel span is within a transceiver bank.
- (4) Side-wide channel bonding is allowed up to the maximum supported by the PHY IP.

Table 25 shows the approximate maximum data rate using the standard PCS.

Table 25. Stratix V Standard PCS Approximate Maximum Date Rate (1), (3)

Mode (2)	Transceiver Speed Grade	PMA Width	20	20	16	16	10	10	8	8
		PCS/Core Width	40	20	32	16	20	10	16	8
FIFO	1	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.5	5.8	5.2	4.72
	2	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.5	5.8	5.2	4.72
		C3, I3, I3L core speed grade	9.8	9.0	7.84	7.2	5.3	4.7	4.24	3.76
	3	C1, C2, C2L, I2, I2L core speed grade	8.5	8.5	8.5	8.5	6.5	5.8	5.2	4.72
		I3YY core speed grade	10.3125	10.3125	7.84	7.2	5.3	4.7	4.24	3.76
		C3, I3, I3L core speed grade	8.5	8.5	7.84	7.2	5.3	4.7	4.24	3.76
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.8	4.2	3.84	3.44
Register	1	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.1	5.7	4.88	4.56
	2	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.1	5.7	4.88	4.56
		C3, I3, I3L core speed grade	9.8	9.0	7.92	7.2	4.9	4.5	3.96	3.6
	3	C1, C2, C2L, I2, I2L core speed grade	10.3125	10.3125	10.3125	10.3125	6.1	5.7	4.88	4.56
		I3YY core speed grade	10.3125	10.3125	7.92	7.2	4.9	4.5	3.96	3.6
		C3, I3, I3L core speed grade	8.5	8.5	7.92	7.2	4.9	4.5	3.96	3.6
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.4	4.1	3.52	3.28

Notes to Table 25:

- (1) The maximum data rate is in Gbps.
- (2) The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.
- (3) The maximum data rate is also constrained by the transceiver speed grade. Refer to Table 1 for the transceiver speed grade.

Table 26 shows the approximate maximum data rate using the 10G PCS.

Table 26. Stratix V 10G PCS Approximate Maximum Data Rate ⁽¹⁾

Mode ⁽²⁾	Transceiver Speed Grade	PMA Width	64	40	40	40	32	32
		PCS Width	64	66/67	50	40	64/66/67	32
FIFO or Register	1	C1, C2, C2L, I2, I2L core speed grade	14.1	14.1	10.69	14.1	13.6	13.6
	2	C1, C2, C2L, I2, I2L core speed grade	12.5	12.5	10.69	12.5	12.5	12.5
		C3, I3, I3L core speed grade	12.5	12.5	10.69	12.5	10.88	10.88
	3	C1, C2, C2L, I2, I2L core speed grade	8.5 Gbps					
		C3, I3, I3L core speed grade						
		C4, I4 core speed grade						
		I3YY core speed grade	10.3125 Gbps					

Notes to Table 26:

- (1) The maximum data rate is in Gbps.
- (2) The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 4 of 5)⁽¹⁾

Symbol/ Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Data rate	GT channels	19,600	—	28,050	19,600	—	25,780	Mbps
Differential on-chip termination resistors	GT channels	—	100	—	—	100	—	Ω
	GX channels	(8)						
V _{OCM} (AC coupled)	GT channels	—	500	—	—	500	—	mV
	GX channels	(8)						
Rise/Fall time	GT channels	—	15	—	—	15	—	ps
	GX channels	(8)						
Intra-differential pair skew	GX channels	(8)						
Intra-transceiver block transmitter channel-to- channel skew	GX channels	(8)						
Inter-transceiver block transmitter channel-to- channel skew	GX channels	(8)						
CMU PLL								
Supported Data Range	—	600	—	12500	600	—	8500	Mbps
t _{PLL_powerdown} ⁽¹³⁾	—	1	—	—	1	—	—	μs
t _{PLL_lock} ⁽¹⁴⁾	—	—	—	10	—	—	10	μs
ATX PLL								
Supported Data Rate Range for GX Channels	VCO post- divider L=2	8000	—	12500	8000	—	8500	Mbps
	L=4	4000	—	6600	4000	—	6600	Mbps
	L=8	2000	—	3300	2000	—	3300	Mbps
	L=8, Local/Central Clock Divider =2	1000	—	1762.5	1000	—	1762.5	Mbps
Supported Data Rate Range for GT Channels	VCO post- divider L=2	9800	—	14025	9800	—	12890	Mbps
t _{PLL_powerdown} ⁽¹³⁾	—	1	—	—	1	—	—	μs
t _{PLL_lock} ⁽¹⁴⁾	—	—	—	10	—	—	10	μs
fPLL								
Supported Data Range	—	600	—	3250/ 3.125 ⁽²³⁾	600	—	3250/ 3.125 ⁽²³⁾	Mbps
t _{PLL_powerdown} ⁽¹³⁾	—	1	—	—	1	—	—	μs

Table 33. Memory Block Performance Specifications for Stratix V Devices⁽¹⁾, ⁽²⁾ (Part 2 of 2)

Memory	Mode	Resources Used		Performance							Unit
		ALUTs	Memory	C1	C2, C2L	C3	C4	I2, I2L	I3, I3L, I3YY	I4	
M20K Block	Single-port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	Simple dual-port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	Simple dual-port with the read-during-write option set to Old Data , all supported widths	0	1	525	525	455	400	525	455	400	MHz
	Simple dual-port with ECC enabled, 512 × 32	0	1	450	450	400	350	450	400	350	MHz
	Simple dual-port with ECC and optional pipeline registers enabled, 512 × 32	0	1	600	600	500	450	600	500	450	MHz
	True dual port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	ROM, all supported widths	0	1	700	700	650	550	700	500	450	MHz

Notes to Table 33:

- (1) To achieve the maximum memory block performance, use a memory block clock that comes through global clock routing from an on-chip PLL set to **50%** output duty cycle. Use the Quartus II software to report timing for this and other memory block clocking schemes.
- (2) When you use the error detection cyclical redundancy check (CRC) feature, there is no degradation in F_{MAX} .
- (3) The F_{MAX} specification is only achievable with Fitter options, **MLAB Implementation In 16-Bit Deep Mode** enabled.

Temperature Sensing Diode Specifications

Table 34 lists the internal TSD specification.

Table 34. Internal Temperature Sensing Diode Specification

Temperature Range	Accuracy	Offset Calibrated Option	Sampling Rate	Conversion Time	Resolution	Minimum Resolution with no Missing Codes
–40°C to 100°C	±8°C	No	1 MHz, 500 KHz	< 100 ms	8 bits	8 bits

Table 35 lists the specifications for the Stratix V external temperature sensing diode.

Table 35. External Temperature Sensing Diode Specifications for Stratix V Devices

Description	Min	Typ	Max	Unit
I_{bias} , diode source current	8	—	200	μA
V_{bias} , voltage across diode	0.3	—	0.9	V
Series resistance	—	—	< 1	Ω
Diode ideality factor	1.006	1.008	1.010	—

Table 36. High-Speed I/O Specifications for Stratix V Devices⁽¹⁾, ⁽²⁾ (Part 2 of 4)

Symbol	Conditions	C1			C2, C2L, I2, I2L			C3, I3, I3L, I3YY			C4,I4			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Transmitter														
True Differential I/O Standards - f_{HSDR} (data rate)	SERDES factor J = 3 to 10 ^{(9), (11), (12), (13), (14), (15), (16)}	(6)	—	1600	(6)	—	1434	(6)	—	1250	(6)	—	1050	Mbps
	SERDES factor J ≥ 4 LVDS TX with DPA ^{(12), (14), (15), (16)}	(6)	—	1600	(6)	—	1600	(6)	—	1600	(6)	—	1250	Mbps
	SERDES factor J = 2, uses DDR Registers	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	Mbps
Emulated Differential I/O Standards with Three External Output Resistor Networks - f_{HSDR} (data rate) ⁽¹⁰⁾	SERDES factor J = 4 to 10 ⁽¹⁷⁾	(6)	—	1100	(6)	—	1100	(6)	—	840	(6)	—	840	Mbps
$t_{x\text{Jitter}}$ - True Differential I/O Standards	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	—	—	160	—	—	160	—	—	160	—	—	160	ps
	Total Jitter for Data Rate < 600 Mbps	—	—	0.1	—	—	0.1	—	—	0.1	—	—	0.1	UI
Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	—	—	300	—	—	300	—	—	300	—	—	325	ps
	Total Jitter for Data Rate < 600 Mbps	—	—	0.2	—	—	0.2	—	—	0.2	—	—	0.25	UI

Table 36. High-Speed I/O Specifications for Stratix V Devices^{(1), (2)} (Part 4 of 4)

Symbol	Conditions	C1			C2, C2L, I2, I2L			C3, I3, I3L, I3YY			C4,I4			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{HSDR} (data rate)	SERDES factor J = 3 to 10	(6)	—	(8)	(6)	—	(8)	(6)	—	(8)	(6)	—	(8)	Mbps
	SERDES factor J = 2, uses DDR Registers	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	Mbps
DPA Mode														
DPA run length	—	—	—	1000 0	—	—	1000 0	—	—	1000 0	—	—	1000 0	UI
Soft CDR mode														
Soft-CDR PPM tolerance	—	—	—	300	—	—	300	—	—	300	—	—	300	\pm PPM
Non DPA Mode														
Sampling Window	—	—	—	300	—	—	300	—	—	300	—	—	300	ps

Notes to Table 36:

- (1) When J = 3 to 10, use the serializer/deserializer (SERDES) block.
- (2) When J = 1 or 2, bypass the SERDES block.
- (3) This only applies to DPA and soft-CDR modes.
- (4) Clock Boost Factor (W) is the ratio between the input data rate to the input clock rate.
- (5) This is achieved by using the **LVDS** clock network.
- (6) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.
- (7) The maximum ideal frequency is the SERDES factor (J) x the PLL maximum output frequency (f_{OUT}) provided you can close the design timing and the signal integrity simulation is clean.
- (8) You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.
- (9) If the receiver with DPA enabled and transmitter are using shared PLLs, the minimum data rate is 150 Mbps.
- (10) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine leftover timing margin.
- (11) The F_{MAX} specification is based on the fast clock used for serial data. The interface F_{MAX} is also dependent on the parallel clock domain which is design-dependent and requires timing analysis.
- (12) Stratix V RX LVDS will need DPA. For Stratix V TX LVDS, the receiver side component must have DPA.
- (13) Stratix V LVDS serialization and de-serialization factor needs to be x4 and above.
- (14) Requires package skew compensation with PCB trace length.
- (15) Do not mix single-ended I/O buffer within LVDS I/O bank.
- (16) Chip-to-chip communication only with a maximum load of 5 pF.
- (17) When using True LVDS RX channels for emulated LVDS TX channel, only serialization factors 1 and 2 are supported.

Table 47. Uncompressed .rbf Sizes for Stratix V Devices

Family	Device	Package	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) ^{(4), (5)}
Stratix V E ⁽¹⁾	5SEE9	—	342,742,976	700,888
	5SEEB	—	342,742,976	700,888

Notes to Table 47:

- (1) Stratix V E devices do not have PCI Express® (PCIe®) hard IP. Stratix V E devices do not support the CvP configuration scheme.
- (2) 36-transceiver devices.
- (3) 24-transceiver devices.
- (4) File size for the periphery image.
- (5) The IOCSR .rbf size is specifically for the CvP feature.

Use the data in Table 47 to estimate the file size before design compilation. Different configuration file formats, such as a hexadecimal (.hex) or tabular text file (.ttf) format, have different file sizes. For the different types of configuration file and file sizes, refer to the Quartus II software. However, for a specific version of the Quartus II software, any design targeted for the same device has the same uncompressed configuration file size. If you are using compression, the file size can vary after each compilation because the compression ratio depends on your design.

- For more information about setting device configuration options, refer to *Configuration, Design Security, and Remote System Upgrades in Stratix V Devices*. For creating configuration files, refer to the *Quartus II Help*.

Table 48 lists the minimum configuration time estimates for Stratix V devices.

Table 48. Minimum Configuration Time Estimation for Stratix V Devices

Variant	Member Code	Active Serial ⁽¹⁾			Fast Passive Parallel ⁽²⁾			
		Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)	
GX	A3	4	100	0.534	32	100	0.067	
		4	100	0.344	32	100	0.043	
	A4	4	100	0.534	32	100	0.067	
	A5	4	100	0.675	32	100	0.084	
	A7	4	100	0.675	32	100	0.084	
	A9	4	100	0.857	32	100	0.107	
	AB	4	100	0.857	32	100	0.107	
	B5	4	100	0.676	32	100	0.085	
	B6	4	100	0.676	32	100	0.085	
	B9	4	100	0.857	32	100	0.107	
	BB	4	100	0.857	32	100	0.107	
	GT	C5	4	100	0.675	32	100	0.084
		C7	4	100	0.675	32	100	0.084

Table 48. Minimum Configuration Time Estimation for Stratix V Devices

Variant	Member Code	Active Serial ⁽¹⁾			Fast Passive Parallel ⁽²⁾		
		Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)
GS	D3	4	100	0.344	32	100	0.043
	D4	4	100	0.534	32	100	0.067
		4	100	0.344	32	100	0.043
	D5	4	100	0.534	32	100	0.067
	D6	4	100	0.741	32	100	0.093
	D8	4	100	0.741	32	100	0.093
E	E9	4	100	0.857	32	100	0.107
	EB	4	100	0.857	32	100	0.107

Notes to Table 48:

(1) DCLK frequency of 100 MHz using external CLKUSR.

(2) Max FPGA FPP bandwidth may exceed bandwidth available from some external storage or control logic.

Fast Passive Parallel Configuration Timing

This section describes the fast passive parallel (FPP) configuration timing parameters for Stratix V devices.

DCLK-to-DATA[] Ratio for FPP Configuration

FPP configuration requires a different DCLK-to-DATA [] ratio when you enable the design security, decompression, or both features. Table 49 lists the DCLK-to-DATA [] ratio for each combination.

Table 49. DCLK-to-DATA[] Ratio ⁽¹⁾ (Part 1 of 2)

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
FPP ×8	Disabled	Disabled	1
	Disabled	Enabled	1
	Enabled	Disabled	2
	Enabled	Enabled	2
FPP ×16	Disabled	Disabled	1
	Disabled	Enabled	2
	Enabled	Disabled	4
	Enabled	Enabled	4

Table 49. DCLK-to-DATA[] Ratio ⁽¹⁾ (Part 2 of 2)

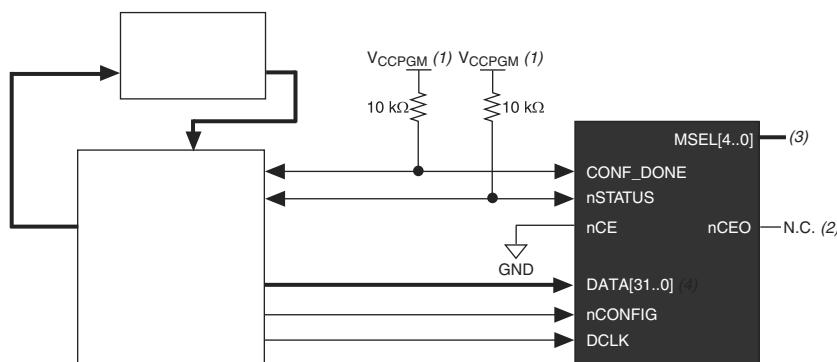
Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
FPP ×32	Disabled	Disabled	1
	Disabled	Enabled	4
	Enabled	Disabled	8
	Enabled	Enabled	8

Note to Table 49:

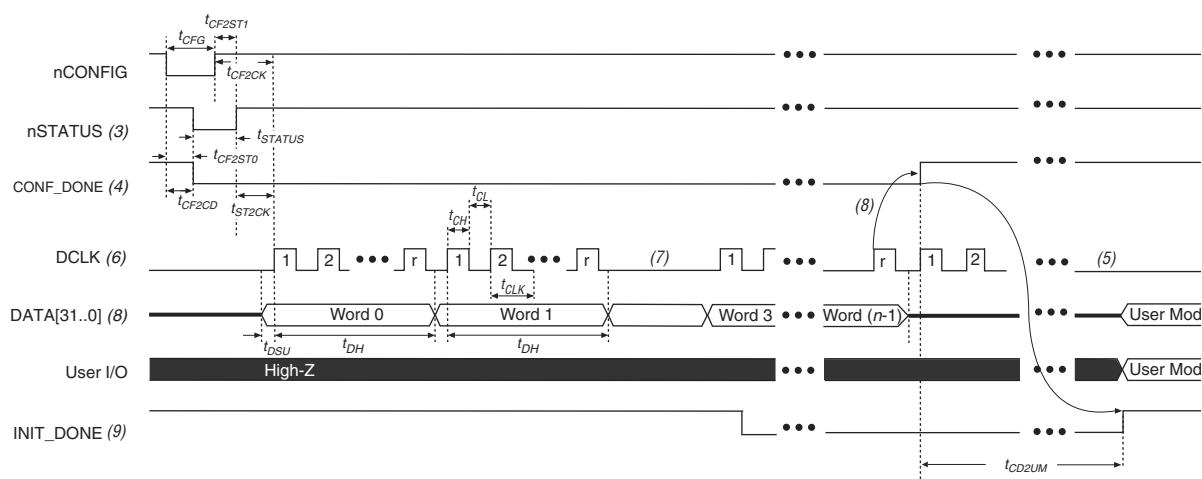
- (1) Depending on the DCLK-to-DATA[] ratio, the host must send a DCLK frequency that is r times the data rate in bytes per second (Bps), or words per second (Wps). For example, in FPP ×16 when the DCLK-to-DATA[] ratio is 2, the DCLK frequency must be 2 times the data rate in Wps. Stratix V devices use the additional clock cycles to decrypt and decompress the configuration data.

 If the DCLK-to-DATA[] ratio is greater than 1, at the end of configuration, you can only stop the DCLK (DCLK-to-DATA[] ratio – 1) clock cycles after the last data is latched into the Stratix V device.

Figure 11 shows the configuration interface connections between the Stratix V device and a MAX II or MAX V device for single device configuration.

Figure 11. Single Device FPP Configuration Using an External Host**Notes to Figure 11:**

- (1) Connect the resistor to a supply that provides an acceptable input signal for the Stratix V device. V_{CCPGM} must be high enough to meet the V_{IH} specification of the I/O on the device and the external host. Altera recommends powering up all configuration system I/Os with V_{CCPGM} .
- (2) You can leave the nCEO pin unconnected or use it as a user I/O pin when it does not feed another device's nCE pin.
- (3) The MSEL pin settings vary for different data width, configuration voltage standards, and POR delay. To connect MSEL, refer to the MSEL Pin Settings section of the “Configuration, Design Security, and Remote System Upgrades in Stratix V Devices” chapter.
- (4) If you use FPP ×8, use DATA [7..0]. If you use FPP ×16, use DATA [15..0].

Figure 13. FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is >1 (1), (2)**Notes to Figure 13:**

- (1) Use this timing waveform and parameters when the DCLK-to-DATA [] ratio is >1. To find out the DCLK-to-DATA [] ratio for your system, refer to Table 49 on page 55.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (3) After power-up, the Stratix V device holds nSTATUS low for the time as specified by the POR delay.
- (4) After power-up, before and during configuration, CONF_DONE is low.
- (5) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (6) “r” denotes the DCLK-to-DATA [] ratio. For the DCLK-to-DATA [] ratio based on the decompression and the design security feature enable settings, refer to Table 49 on page 55.
- (7) If needed, pause DCLK by holding it low. When DCLK restarts, the external host must provide data on the DATA [31 .. 0] pins prior to sending the first DCLK rising edge.
- (8) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (9) After the option bit to enable the INIT_DONE pin is configured into the device, the INIT_DONE goes low.

Table 51 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA [] ratio is more than 1.

Table 51. FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1⁽¹⁾

Symbol	Parameter	Minimum	Maximum	Units
t_{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t_{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t_{CFG}	nCONFIG low pulse width	2	—	μs
t_{STATUS}	nSTATUS low pulse width	268	1,506 ⁽²⁾	μs
t_{CF2ST1}	nCONFIG high to nSTATUS high	—	1,506 ⁽²⁾	μs
$t_{CF2CK}^{(5)}$	nCONFIG high to first rising edge on DCLK	1,506	—	μs
$t_{ST2CK}^{(5)}$	nSTATUS high to first rising edge of DCLK	2	—	μs
t_{DSU}	DATA [] setup time before rising edge on DCLK	5.5	—	ns
t_{DH}	DATA [] hold time after rising edge on DCLK	$N-1/f_{DCLK}^{(5)}$	—	s
t_{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	—	s
t_{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	—	s
t_{CLK}	DCLK period	$1/f_{MAX}$	—	s
f_{MAX}	DCLK frequency (FPP ×8/×16)	—	125	MHz
	DCLK frequency (FPP ×32)	—	100	MHz
t_R	Input rise time	—	40	ns
t_F	Input fall time	—	40	ns
t_{CD2UM}	CONF_DONE high to user mode ⁽³⁾	175	437	μs
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	$4 \times$ maximum DCLK period	—	—
t_{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (8576 \times$ CLKUSR period) ⁽⁴⁾	—	—

Notes to Table 51:

- (1) Use these timing parameters when you use the decompression and design security features.
- (2) You can obtain this value if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (3) The minimum and maximum numbers apply only if you use the internal oscillator as the clock source for initializing the device.
- (4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the “Configuration, Design Security, and Remote System Upgrades in Stratix V Devices” chapter.
- (5) N is the DCLK-to-DATA ratio and f_{DCLK} is the DCLK frequency the system is operating.
- (6) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

Table 53. AS Timing Parameters for AS ×1 and AS ×4 Configurations in Stratix V Devices^{(1), (2)} (Part 2 of 2)

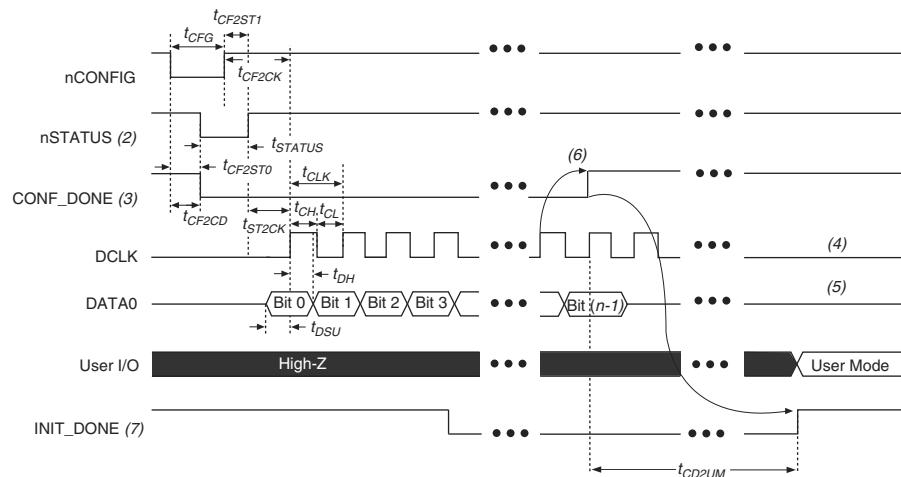
Symbol	Parameter	Minimum	Maximum	Units
t_{CD2UM}	CONF_DONE high to user mode ⁽³⁾	175	437	μs
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
t_{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (8576 \times$ CLKUSR period)	—	—

Notes to Table 53:

- (1) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- (2) t_{CF2CD} , t_{CF2STO} , t_{CFG} , t_{STATUS} , and t_{CF2ST1} timing parameters are identical to the timing parameters for PS mode listed in Table 54 on page 63.
- (3) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the Initialization section of the “Configuration, Design Security, and Remote System Upgrades in Stratix V Devices” chapter.

Passive Serial Configuration Timing

Figure 15 shows the timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.

Figure 15. PS Configuration Timing Waveform⁽¹⁾**Notes to Figure 15:**

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (3) After power-up, before and during configuration, CONF_DONE is low.
- (4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (5) DATA0 is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the **Device and Pins Option**.
- (6) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (7) After the option bit to enable the INIT_DONE pin is configured into the device, the INIT_DONE goes low.

Table 58. IOE Programmable Delay for Stratix V Devices (Part 2 of 2)

Parameter (1)	Available Settings	Min Offset (2)	Fast Model		Slow Model							
			Industrial	Commercial	C1	C2	C3	C4	I2	I3, I3YY	I4	Unit
D3	8	0	1.587	1.699	2.793	2.793	2.992	3.192	2.811	3.047	3.257	ns
D4	64	0	0.464	0.492	0.838	0.838	0.924	1.011	0.843	0.920	1.006	ns
D5	64	0	0.464	0.493	0.838	0.838	0.924	1.011	0.844	0.921	1.006	ns
D6	32	0	0.229	0.244	0.415	0.415	0.458	0.503	0.418	0.456	0.499	ns

Notes to Table 58:

- (1) You can set this value in the Quartus II software by selecting **D1**, **D2**, **D3**, **D5**, and **D6** in the **Assignment Name** column of **Assignment Editor**.
(2) Minimum offset does not include the intrinsic delay.

Programmable Output Buffer Delay

Table 59 lists the delay chain settings that control the rising and falling edge delays of the output buffer. The default delay is 0 ps.

Table 59. Programmable Output Buffer Delay for Stratix V Devices (1)

Symbol	Parameter	Typical	Unit
D_{OUTBUF}	Rising and/or falling edge delay	0 (default)	ps
		25	ps
		50	ps
		75	ps

Note to Table 59:

- (1) You can set the programmable output buffer delay in the Quartus II software by setting the **Output Buffer Delay Control** assignment to either positive, negative, or both edges, with the specific values stated here (in ps) for the **Output Buffer Delay** assignment.

Glossary

Table 60 lists the glossary for this chapter.

Table 60. Glossary (Part 1 of 4)

Letter	Subject	Definitions
A	—	—
B	—	—
C	—	—
D	—	—
E	—	—
F	f_{HSCLK}	Left and right PLL input clock frequency.
	f_{HSDR}	High-speed I/O block—Maximum and minimum LVDS data transfer rate ($f_{HSDR} = 1/TUI$), non-DPA.
	$f_{HSDRDPA}$	High-speed I/O block—Maximum and minimum LVDS data transfer rate ($f_{HSDRDPA} = 1/TUI$), DPA.